

Environmental Compliance Evaluation Report

Product Name : Server

Product Model : See Page 3

Report Number : SYBH(G)08097394

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Notice

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Applicant : xFusion Digital Technologies Co., Ltd.
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Manufacturer : Same as applicant
Address : Same as applicant
Product Name : Server
Product Model : 2158H V8*****, FusionServer 2158H V8***** (where "*" can be 0-9,a-z,A-Z,"-" or Blank for marketing purpose)
Date of Sample Receiving : 2025-02-28
Start Date of Evaluation : 2025-02-28
End Date of Evaluation : 2025-03-03

Evaluation Result :

Regulation/Directive	Conclusion
EU RoHS (2011/65/EU & (EU) 2015/863) & UK RoHS	Comply
SVHC in accordance with Article 59(1) of the Regulation (EC) No 1907/2006 (REACH)	See Clause 5.1
Regulation (EC) No 1907/2006 (REACH) Annex XVII	Comply
94/62/EC & 2004/12/EC for Packaging Material & The Packaging (Essential Requirements) Regulations 2015	Comply
EU WEEE (2012/19/EU) ANNEX V & UK WEEE SCHEDULE 11 PART 2	Comply
EU POPs ((EU) 2019/1021) & UK POPs	Comply
China RoHS (Decree No. 32 of the Chinese Ministry of Industry and Information Technology)	Comply

Approved by Senior Engineer: 2025-03-05 Huang Xuan *Huang Xuan*

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Date Name Signature

Modification Record

No.	Last Report No.	Modification Description
1	N/A	First report

Remark: This report is evaluated based on the documents and declarations of material environmental compliance provided by the applicant.

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List of abbreviations

No.	Abbreviations	Full spelling
1	RoHS	the Restriction of the use of certain hazardous substances in electrical and electronic equipment
2	REACH	REGULATION concerning the Registration, Evaluation, Authorisation and Restriction of Chemicals
3	SVHC	Substances of Very High Concern
4	WEEE	Waste Electrical and Electronic Equipment
5	MCD	Material Composition Declaration
6	BOM	Bill of Materials
7	PDM	Product Data Management
8	Insight	Product Compliance Management Platform
9	ppm	parts per million
10	ppb	parts per billion
11	NA	Not Applicable
12	ND	Not Detected (Less than the method limits for the test lab)
13	3R	Recovery, Reuse and Recycling

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1 General Information

1.1 Applied Standards

Applied Regulations & Standards :

- Directive 2011/65/EU & (EU) 2015/863 (EU RoHS)
- The Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment Regulations 2012 (UK RoHS)
- IEC 63000:2016&EN IEC 63000: 2018 & BS EN IEC 63000: 2018
- Regulation (EC) No 1907/2006 (REACH)
- Directive 94/62/EC (EU Packaging Directive)
- The Packaging (Essential Requirements) Regulations 2015 (UK Packaging Regulations)
- Regulation (EU) 2019/1021 (EU POPs)
- The Persistent Organic Pollutants Regulations 2007 (UK POPs)
- Directive 2012/19/EU (EU WEEE) ANNEX V
- The Waste Electrical and Electronic Equipment Regulations 2013 (UK WEEE) SCHEDULE 11 PART 2
- China RoHS (Decree No. 32 of the Chinese Ministry of Industry and Information Technology)
- GB/T 36560-2018 Specifications for technical documentation for the conformity demonstration of electrical and electronic products with respect to the restriction of hazardous substances

Test Methods : See details in the report

1.2 Company to perform the evaluation

Company name : Reliability Laboratory of xFusion Digital Technologies Co., Ltd.

Company Address : Block A, Bojin International (Bojin Business Plaza), No. 1 Tairan 7th Road, Chegongmiao, Futian District, Shenzhen, P.R.C

2 Product Description

2.1 General description

The 2158H V8***** , FusionServer 2158H V8***** (where "*"can be 0-9,a-z,A-Z,"-" or Blank for marketing purpose) is a new-generation 2U 1-socket rack server designed for the Internet, Internet Data Center (IDC), cloud computing, enterprise business, and telecom.This product is ideal for IT core services, cloud computing, virtualization, high-performance computing, distributed storage, big data processing, enterprise or telecom applications, and other complex workloads.This product features low power consumption, high scalability, high reliability, and easy management and deployment.

2.2 Product photos



3 Review of the Documents of Conformity

According to IEC 63000:2016, EN IEC 63000: 2018 and BS EN IEC 63000: 2018, the manufacturer shall collect supplier declarations and/or contractual agreements, and/or material declarations and/or analytical test results for materials, parts, and/or sub-assemblies from all suppliers. As per xFusion's requirements, all suppliers shall sign the supplier declarations (*Quality and Environment Assurance Agreement* and *Indemnity Agreement for Quality and Environment Problems of Supplier's Materials* and/or *Declaration of Non-use of Restricted Substances* which declares that suppliers' products meet the requirement of EU RoHS, REACH, packaging directive, POPs and Proposition 65 of California) and provide the MCDs (Material Composition Declaration) to prove that their products comply with all of above requirements. Additionally, the analytical test reports of high risk materials (identified by the manufacturer) shall be provided.

Based on the evaluation of quality and trustworthiness of these documents, xFusion decides that the documents provide sufficient evidence of compliance and shall be included in the technical documentation.

Remark: The battery, which is integrated in the server and covered by Regulation (EU) 2023/1542, is produced by other manufacturers, so this report doesn't cover the evaluation of the battery. xFusion will require the battery manufacturer to strictly follow the requirements of Regulation (EU) 2023/1542.

4 The Evaluation of RoHS Compliance

4.1 The Evaluation of Materials/Samples

According to EN IEC 63000: 2018 and BS EN IEC 63000: 2018, the related documents (supplier declarations and MCDs) are collected from the suppliers of the materials, parts and sub-assemblies (see chapter 3 of this report), and high-risk materials identified are tested by the suppliers. The qualified procedure is established to evaluate all of these documents collected. As per the Directive 2011/65/EU and amendments, and UK RoHS, the evaluation results are summarized in Table 3.

4.2 The Test of High Risk Material/Samples

The high risk materials tested are listed below:

(1) High Risk Materials/Samples Information

Table 1 Evaluation results of high risk materials / samples for RoHS

Item	Evaluation of High Risk Materials / Samples		
High Risk Material Information	Amount		
	High Risk Samples in Product ¹	Tested Samples	Failed Samples
	32	32	0
Result ²	Comply		

Remark:

- As per xFusion's "Guide to Grading RoHS Compliance Risk Levels of Materials", and "Annex D in GB/T26572", the high risk materials include solder (Pb), plating layer (Pb, Cr(VI)), plastic colorant (Pb, Cd and Cr(VI)), ABS (Acrylonitrile Butadiene Styrene) plastic (PBDE), PVC (Polyvinyl Chloride) plastic (Pb, Cd), PP (Polypropylene) plastic (PBDE), PET (Polyester Terephthalate) plastic (PBDE), PBT (Polybutylene Terephthalate) plastic (PBDE), coatings (Pb), cable jacketing and other soft plastics (phthalate substances DEHP, BBP, DBP and DIBP) and alloy (Pb, Cd and Cr(VI)).
- The results are based on the evaluation results and the exemptions in EU RoHS & UK RoHS, and all exemptions applied to the evaluated product materials are taken as "Pass" for the evaluation results.

(2) Test Items and Methods of the High Risk Materials

As per the information provided by the suppliers, the high risk materials are tested with the following methods.

Table 2 Test Methods of High Risk Materials for RoHS

Test Items	Test Methods
Cadmium (Cd)	With reference to EN/IEC 62321-5, by acid digestion and determined by ICP-OES
Lead (Pb)	
Mercury (Hg)	With reference to EN/IEC 62321-4, by acid digestion and determined by ICP-OES
Hexavalent chromium [Cr(VI)]	With reference to EN/IEC 62321-7-1 & EN/IEC 62321-7-2 by solvent extraction and determined by UV-VIS
Polybrominated biphenyls (PBB)	With reference to EN/IEC 62321-6, by solvent extraction and determined by GC/MS
Polybrominated diphenyl ethers (PBDE)	
Bis(2-ethylhexyl) phthalate (DEHP)	With reference to EN/IEC 62321-8, by solvent extraction and determined by GC/MS
Butyl benzyl phthalate (BBP)	
Dibutyl phthalate (DBP)	
Diisobutyl phthalate (DIBP)	

4.3 Evaluation Results

The limits of restricted substances are quoted from EU RoHS and UK RoHS for homogeneous material and the results are shown in Table 3.

Table 3 Evaluation Results against RoHS Restricted Substances Limits

Restricted Substances	Limits	Contents in material/sample
Cadmium (Cd)	0.01% (100 ppm)	ND
Lead (Pb)	0.1% (1000 ppm)	ND
Mercury (Hg)	0.1% (1000 ppm)	ND
Hexavalent chromium [Cr(VI)]	0.1% (1000 ppm)	ND
Polybrominated Biphenyls (PBB)	0.1% (1000 ppm)	ND
Polybrominated Diphenyl Ethers (PBDE)	0.1% (1000 ppm)	ND
Bis(2-ethylhexyl) phthalate (DEHP)	0.1% (1000 ppm)	ND
Butyl benzyl phthalate (BBP)	0.1% (1000 ppm)	ND
Dibutyl phthalate (DBP)	0.1% (1000 ppm)	ND
Diisobutyl phthalate (DIBP)	0.1% (1000 ppm)	ND

Remark: The evaluation results are based on the full configuration of the product (See Annex II).

5 The Evaluation of REACH Compliance

5.1 The Evaluation of REACH SVHC

Based on the documents collected from the suppliers of material, parts and sub-assemblies (see chapter 3 of this report), the evaluation against the substances in the most updated *Candidate List of Substances of Very High Concern (SVHC) for authorization published by European Chemicals Agency (ECHA)* regarding Regulation (EC) No 1907/2006 concerning the REACH is performed. The SVHC in a concentration above 0.1% (w/w) of "article" in the product (including batteries and packaging materials) identified are listed as below.

Table 4 SVHC in a concentration above 0.1% weight by weight

SVHC in a concentration above 0.1% weight by weight	CAS No.
1,3,5-TRIS(OXIRAN-2-YLMETHYL)-1,3,5-TRIAZINANE-2,4,6-TRIONE (TGIC)	2451-62-9
OCTAMETHYLCYCLOTETRASILOXANE	556-67-2
1, 2-DIMETHOXYETHANE; ETHYLENE GLYCOL DIMETHYL ETHER (EGDME)	110-71-4
2,2',6,6'-TETRABROMO-4,4'-ISOPROPYLIDENEDIPHENOL	79-94-7
2-(DIMETHYLAMINO)-2-[(4-METHYLPHENYL)METHYL]-1-[4-(MORPHOLIN-4-YL)PHENYL]BUTAN-1-ONE	119344-86-4
DIPHENYL(2,4,6-TRIMETHYLBENZOYL)PHOSPHINE OXIDE	75980-60-8
4,4'-ISOPROPYLIDENEDIPHENOL	80-05-7
TRIPHENYL PHOSPHATE	115-86-6
N,N-DIMETHYLACETAMIDE	127-19-5
LEAD	7439-92-1

Remark:

- Article 33 of (EC) No. 1907/2006 requires supplier of an article containing SVHC in a concentration above 0.1% weight by weight shall provide the recipient of the article with sufficient information, available to the supplier, to allow safe use of the article including, as a minimum, the name of that SVHC.
- "Article" in product means an object which during production is given a special shape, surface or design which determines its function to a greater degree than does its chemical composition (according to Regulation (EC) No 1907/2006). The limit of 0.1% (w/w) applies to every article in the product. The results are calculated based on an article defined by decision C-106/14 of EuGH of 10th September 2015.
- In accordance with Regulation (EC) No 1907/2006, any EU producer or importer of articles shall notify ECHA, in accordance with paragraph 4 of article 7, if a substance meets the criteria in Article 57 and is identified in accordance with Article 59(1) of the regulation, if (a) the substance in the Candidate List is present in those articles in quantities totaling over one tonne per producer or importer per year; and (b) the substance in Candidate List is present in those articles above a concentration of 0.1% weight by weight (W/W) .
- The evaluation results are based on the full configuration of the product (See Annex II).

In conclusion, after the evaluation, 10 SVHCs in a concentration above 0.1% weight by weight are identified and listed in above Table 4.

5.2 The Evaluation against Annex XVII to REACH

Based on the documents collected from the suppliers of material, parts and sub-assemblies (see chapter 3), the restricted substances listed in Annex XVII (if applicable) to REACH Regulation are evaluated. The evaluation results are described in the Table below.

Table 5 The Evaluation Results against Annex XVII to REACH (if applicable)

Material Descriptions	Restricted Substances	Requirements	Content in material/sample
All Materials	Monomethyl – tetrachlorodiphenylmethane (Ugilec 141)	Prohibited	ND
All Materials	Monomethyl-dichloro-diphenyl methane (Ugilec 121, Ugilec 21)	Prohibited	ND
All Materials	Monomethyl - dibromo - diphenylmethane, bromobenzyl toluene (DBBT)	Prohibited	ND
All Materials	Dimethyl fumarate (DMF)	0.1ppm	ND
All Materials	Asbestos fiber	Prohibited	ND
All Materials	Organotin compounds	total content < 1000 ppm	ND
All Materials	Benzene	Prohibited	ND
All Materials	Polychlorinated terphenyls and their derivatives (PCTs)	50ppm	ND
Dye or colorant for plastics, textiles, leather products	Azo dyes	30ppm	ND
Direct and long contact with the skin of the electroplating, corrosion-resistant alloy materials	Nickel and its compounds	0.5 µg/cm ² / week	ND
textiles, leather products	Nonylphenol (NP) Nonylphenol polyoxyethylene ether (NPEO)	100ppm	NA
textiles	Tris (2,3-dibromopropyl) phosphate (TRIS)	Shall not be used	NA
textiles	Tri- (aziridinyl) phosphine oxide (TEPA)	Shall not be used	NA
Wooden packaging material	Arsenic and its compounds	Shall not be used	ND
Wooden packaging material	Creosote, naphthalene oil, anthracene oil, tar acid, alkaline low temperature tar etc.	Shall not be used	ND
Rubber or plastic material on the exterior or user contact surface of the product	Polycyclic Aromatic Hydrocarbons (PAHs)	Single PAHs substance (BaP;BeP;BaA;BbFA;BjFA;BkFA;CHR;DBAhA;Benzo[g,h,i]perylene;Indeno[1,2,3-cd]pyrene) < 1ppm	ND
Thermal paper	Bisphenol A	200ppm	NA
All materials	Phenylmercury	100ppm(the concentration of mercury)	ND

Remark: The evaluation results are based on the full configuration of the product (See Annex II).

In conclusion, as per the results shown in Table 5, the contents of restricted substances in submitted sample comply with the requirements of Annex XVII to REACH (if applicable).

6 The Evaluation against Restricted Substances Requirements in Packaging Directive

Based on the documents collected from the suppliers of the packages (see chapter 3), the restricted substances regulated in the EU Packaging Directive (94/62/EC) and UK Packaging Regulations (The Packaging (Essential Requirements) Regulations 2015) are evaluated. The evaluation results are listed in Table 6.

Table 6 The Evaluation Results against Restricted Substance Requirements in the Packaging Regulations

Material Descriptions	Report No.	Requirements in Directive 94/62/EC & UK Packaging Regulations	Content of Restricted Substances (ppm)				
			Cd	Pb	Hg	Cr(VI)	Sum
All materials in the packages	-	The sum of Cd, Pb, Hg and Cr(VI) < 100 ppm	ND	ND	ND	ND	<100
Conclusion		Comply					

The evaluation of SVHC contained in the packaging materials are specified in chapter 5.1.

7 The Evaluation of POPs Compliance

According to EU POPs Regulation (EU) 2019/1021 & UK POPs Regulation (The Persistent Organic Pollutants Regulations 2007), the manufacturing, placing on the market and use of substances listed in Annex I & Annex II, whether on their own, in mixtures or in articles, shall be prohibited. Unless it complies with the following conditions:

- (a) a substance used for laboratory-scale research or as a reference standard;
- (b) a substance presented as an unintentional trace contaminant, as specified in the relevant entries of Annex I or II, in substances, mixtures or articles.

Based on the documents collected from the suppliers of the materials, parts and sub-assemblies (see chapter 3), the prohibited substances listed in (EU) 2019/1021 and UK POPs Regulation specified in the paragraph 1 of this chapter, if applicable, are evaluated. The evaluation results are described in Table 7.

Table 7 Evaluation Results against prohibited substances of POPs Regulation (if applicable)

Material Descriptions	Prohibited Substances	Limit	Contents in material / sample
All Materials	Tetrabromodiphenyl ether, Pentabromodiphenyl ether, Hexabromodiphenyl ether, Heptabromodiphenyl ether, Decabromodiphenyl ether	1000ppm (follow the limits defined in RoHS Directive)	ND
All Materials (except textiles and coated materials)	Perfluorooctane sulfonic acid and its derivatives (PFOS)	1000ppm	ND
Textiles or other coated materials		1 µg/ m ²	ND

All Materials	Hexachlorobenzene	Shall not be used	ND
All Materials	Pentachlorobenzene	Shall not be used	ND
All Materials	Polychlorinated Biphenyls (PCB)	Shall not be used	ND
All Materials	Hexabromobiphenyl	Shall not be used	ND
All Materials	Hexabromocyclododecane	100ppm	ND
All Materials	Hexachlorobutadiene	Shall not be used	ND
All Materials	Pentachlorophenol and its salts and esters	5ppm	ND
All Materials	Polychlorinated naphthalenes(PCNs)	Shall not be used	ND
All Materials	Alkanes C10-C13, chloro (short-chain chlorinated paraffins) (SCCPs)	1500ppm	ND
All Materials	Perfluorooctanoic acid (PFOA), its salts	25ppb	ND
All Materials	Perfluorooctanoic acid (PFOA)related substances	1ppm	ND
Packaging Materials, Transport Materials	DDT (1,1,1-trichloro-2,2-bis(4-chlorophenyl)ethane),Chlordane , Hexachlorocyclohexanes including lindane, Dieldrin, Endrin, Heptachlor, Endosulfan, Chlordecone, Aldrin, Mirex, Toxaphene, Dicofol	Shall not be used	ND

Remark: The evaluation results are based on the full configuration of the product (See Annex II).

In conclusion, as per the results shown in Table 7, the contents of prohibited substances in submitted sample comply with the requirements of Annex I to EU POPs Regulation and UK corresponding regulation.

8 WEEE 3R (Recovery, Recycling & Reuse) Evaluation

8.1 WEEE 3R Results

According to the evaluation process of WEEE 3R described in chapter 9.2, the below result can be gotten in below Table:

Table 8 Conclusion of WEEE 3R for Evaluated Product

Product Name	Server	
Product Category	Large equipment excluding photovoltaic panels	
Reuse/recycling/recovery (3R)	Recovery (%)	Reuse & Recycling (%)
Evaluation Result	94.12%	90.36%
3R Requirements in WEEE for the Product	85%	80%
3R Compliance for the Product	Comply	Comply

8.2 WEEE 3R Calculation

As per xFusion's evaluation instructions of WEEE 3R and IEC TR 62635-62650, referencing the actual 3R data of EEE products, we analysis the materials/parts information incorporated in the Insight system. Finally, the results of 3R of this Server are listed in Table 9:

Table 9 Results of WEEE 3R for Evaluated Product

Material / Part Description	Weight Ratio (%)	Recoverability Rate (%)	Reuse and Recyclability Rate (%)	Weight Ratio of Recovery (%)	Weight Ratio of Reuse & Recycling (%)
(1) Parts required selective treatment					
Power Cable	2.30%	90%	85%	2.07%	1.96%
Capacitor (PCB/PCT)	0.00%	90%	85%	0.00%	0.00%
PCB (Printed Circuit Board)	17.64%	90%	70%	15.88%	12.35%
BFR* Plastics	0.00%	90%	0%	0.00%	0.00%
Electrolyte Capacitors	0.00%	0%	0%	0.00%	0.00%
(2) Parts difficult to process					
Compressors	0.00%	90%	90%	0.00%	0.00%
AC Motor	0.00%	90%	90%	0.00%	0.00%
Resin Motor	0.00%	0%	0%	0.00%	0.00%
Transformer (MWO)	0.00%	90%	90%	0.00%	0.00%
(3) Parts which go to separation process					
ABS (Acrylonitrile Butadiene Styrene)	1.73%	90%	90%	1.56%	1.56%
PC (Polycarbonate)	4.36%	90%	90%	3.92%	3.92%
PET (Polyethylene Terephthalate)	0.00%	90%	90%	0.00%	0.00%
PP (Polypropylene)	0.00%	90%	90%	0.00%	0.00%
PS (Polystyrene)	0.00%	90%	90%	0.00%	0.00%
PBT (Polybutylene terephthalate)	0.00%	90%	90%	0.00%	0.00%
PVC (Polyvinyl chloride)	0.00%	90%	0%	0.00%	0.00%
POM (Polyoxymethylene)	0.00%	90%	90%	0.00%	0.00%
EP (Epoxy Resin)	0.00%	90%	0%	0.00%	0.00%
Steel	65.22%	98%	98%	63.92%	63.92%
Aluminum	1.40%	98%	98%	1.37%	1.37%
Copper	0.08%	98%	98%	0.08%	0.08%
Zinc	2.42%	98%	98%	2.37%	2.37%
Rubber	0.13%	90%	0%	0.12%	0.00%
Fiberglass	0.00%	80%	80%	0.00%	0.00%
Others	4.71%	60%	60%	2.83%	2.83%
Total	100.00%	-	-	94.12%	90.36%

Remark:

- Abbreviations are listed as below:

3R	=	Recovery, Reuse and Recycling
WEEE	=	Waste Electrical and Electronic Equipment
BFR*	=	Brominated Flame Retardants

- The evaluation results are based on the typical configuration of the product (See Annex III).

3. According to EU WEEE& UK WEEE, Reuse, Recycling & Recovery Rate using in the report are calculated as following formulas.

$$\text{Recovery Rate (\%)} = \frac{\text{Reuse \& Recycling Weight} + \text{Energy Recovery Weight}}{\text{Product Total Weight}} \times 100\%$$

$$\text{Reuse \& Recycling Rate (\%)} = \frac{\text{Reuse \& Recycling Weight}}{\text{Product Total Weight}} \times 100\%$$

8.3 Preparation for Recovery, Recycling and Reuse of the Product

According to Articles 8 and the Annex VII of Directive 2012/19/EU (WEEE Directive), the following substances, mixtures and components listed in Table 10 have to be removed and be selectively treated when during the evaluation.

Table 10 Removed Components in the Product

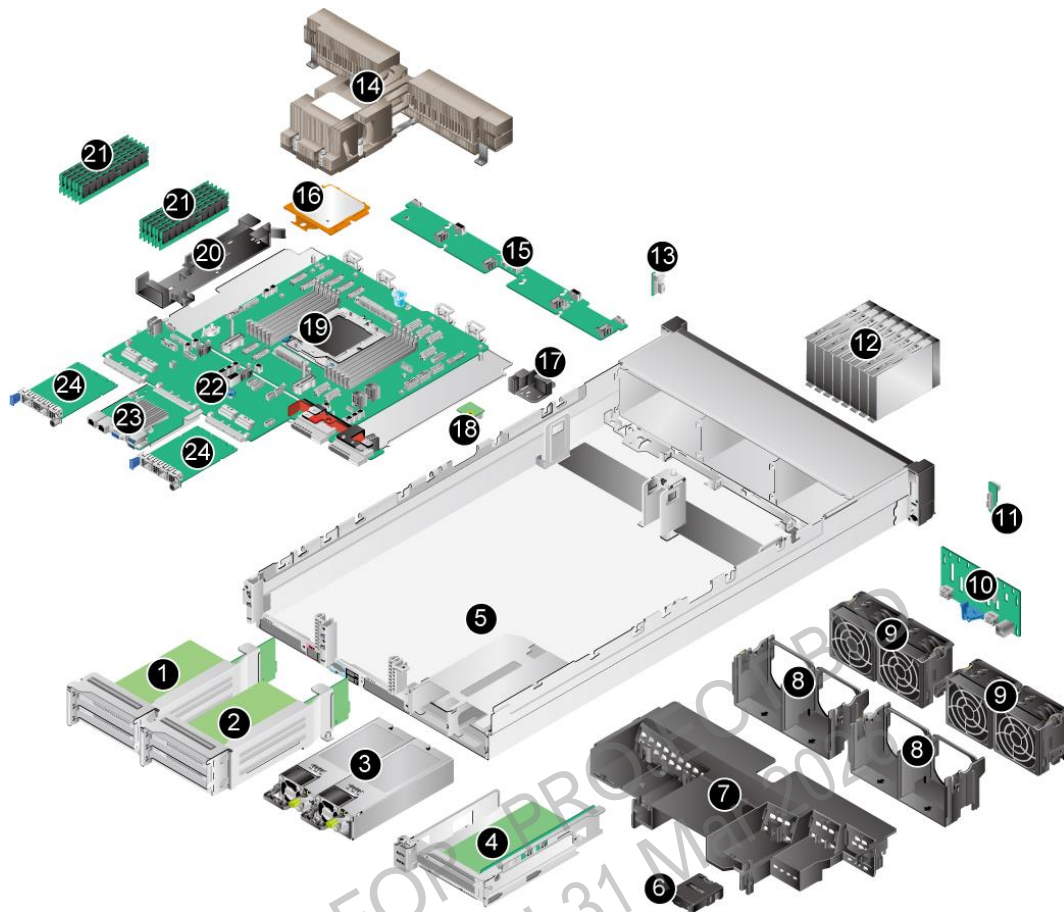
Descriptions of Parts and Materials	Remarks	Quantity
Capacitors / condensers (Containing PCB/PCT)	Polychlorinated biphenyls and polychlorinated terphenyls (PCB/PCT)	0
Mercury-containing components	Such as mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Printed Circuit Boards (PCB) or Printed Circuit Board Assemblies (PCBA)	Printed circuit boards of mobile phones generally, and of other devices if the surface of the printed circuit board is greater than 10 square centimeters	8
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations	0
Plastics containing Brominated Flame Retardants	Brominated Flame Retardants include PBB, PBDE, HBCDD and so on	0
Components and waste containing asbestos	-	0
Cathode Ray Tubes (CRT)	-	0
Chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons (HFC), hydrocarbons (HC)	-	0
Gas Discharge Lamps	-	0

Liquid Crystal Displays (LCD)	With a surface greater than 100 sq cm, includes background illuminated displays with gas discharge lamps	0
External electrical cables and cords	-	4
Components, parts and materials containing refractory ceramic fibres	Described in Commission Directive 97/69/EC adapting to technical progress Council Directive 67/548/EEC relating to the classification, packaging and labeling of dangerous substances (2)	0
Components, parts and materials containing radioactive substances	With the exception of components that are below the exemption thresholds set in Article 3 of an Annex I to Council Directive 96/29/Euratom laying down basic safety standards for the protection of the health of workers and the general public against the dangers arising from ionizing radiation (3)	0
Electrolyte capacitors containing substances of concern	Height > 25 mm, diameter > 25 mm or proportionately similar volume	0

8.4 Sketch Figure of Sample Disassembly

The disassembly procedure taken here is in accordance with the treatment requirements under EU WEEE & UK WEEE, and based on economic and efficiency factor, disassembly tools, and current state of the art of recycling and recovery technology. The detailed information for sample disassembly can be described as below in Figure 1.

Figure 1 Sketch Figure of Evaluated Sample Disassembly



1	I/O module 1	2	I/O module 2
3	PSU	4	I/O module 3
5	Chassis	6	Supercapacitor holder
7	Air duct	8	Fan module brackets
9	Fan modules	10	Front-drive backplane
11	Left mounting ear plate	12	Front drives
13	Right mounting ear plate	14	Processor heat sink
15	Fan board	16	Processor
17	Cable organizer	18	TPM/TCM
19	Mainboard	20	Cable organizer
21	Memory modules	22	IO Board
23	BMC card	24	OCP 3.0 NIC

Annex I China RoHS Hazardous Substances Information Evaluation

According to China RoHS (the Administrative Measures for the Restriction of the Use of Hazardous Substances in Electrical and Electronic Products on Jan 21, 2016, with it coming into effect on July 1, 2016., Decree No. 32 of the Chinese Ministry of Industry and Information Technology), a Hazardous Substance table must also be supplied with the product that lists each part that is out of compliance. As per the evaluation process and the data in InSight System, the below table was made for the product and its fittings.

Table 1 Hazardous Substances Table in Product

部件名称 Part Descriptions	有害物质 Hazardous Substances					
	镉 Cd	铅 Pb	汞 Hg	六价铬 Cr(VI)	多溴联苯 PBB	多溴二苯醚 PBDE
印制电路板组件 PCBA	○	×	○	○	○	○
电缆 Cables	○	×	○	○	○	○
金属部件 Metal Parts	○	×	○	○	○	○
聚合物部件 Polymeric Parts	○	○	○	○	○	○
电池 Batteries	○	×	○	○	○	○

Remark: The table is prepared in accordance with SJ/T 11364.

- : It means that the content of the restricted substance in all materials of part is less than the limit defined in GB/T 26572 and other similar directives in other countries.
- × : It means that the content of the restricted substance in at least one homogenous material of part is not less than the limit defined in GB/T 26572 and other similar directives in other countries.

The "×" in the above table indicates that one or more exemptions are applied in these parts.

AnnexII Full Configuration of Product

Board list		
Board Name	Description	Qty.
BC26FDTA	Manufactured Board,2158H V8,BC26FDTA, AMD Server 2U1P Fan Board 6*6056,1*2	1
BC26IOTB	Manufactured Board,2158H V8,BC26IOTB, AMD Server 2U1P IO Board(GPU Server),1*2	1
BC26IOTA	Manufactured Board,2158H V8,BC26IOTA, AMD Server 2U1P IO Board,1*1	1
BC26HBMA	Manufactured Board,2158H V8,BC26HBMA,BC26HBMA,1*1	1
BC26SMMA	Manufactured Board,2158H V8,BC26SMMA, AMD Server 1711 DC-SCM BMC Card,2*1	1
BC26HBBA	Manufactured Board,2158H V8,BC26HBBA, 8*3.5" SAS/SATA/NVME HDD Backplane Board,1*2	1
BC26MBTA	Manufactured Board,2158H V8,BC26MBTA, AMD Server 2U1P Main Board,1*1	1
BC15HBBS	Manufactured Board,2258 V7,BC15HBBS, IO3 4*NVMe HDD backplane,1*4	1
BC15NHBR	Manufactured Board,2258 V7,BC15NHBR, 12*3.5" SAS/SATA/NVMe HDD backplane,1*2	1
BC55RLAH1	Manufactured Board,Public Module,BC55RLAH1, XP270-M2-(SAS3808)-M.2 RAID PCIE card-RAID0, 1,JBOD-No CacheSupport Sideband Management,1*2	1
BC15HBBK	Manufactured Board,2288DX V7,BC15HBBK, 8*2.5" SAS/SATA HDD backplane,1*2	1
BC15NHBK	Manufactured Board,2288H V7,BC15NHBK, 8*2.5" SAS/SATA/NVMe HDD backplane,1*2	1
BC15PRUW	Manufactured Board,G5500 V7,BC15PRUW, Back PCIe Riser Card(1*X16 PCIe 5.0 UBCDD-CEM),1*1	1
BC15NHBI	Manufactured Board,2288H V7,BC15NHBI, 8*SAS/SATA+16NVME HDD BP,1*2	1
BC15PRUR	Manufactured Board,2288H V7,BC15PRUR, IO1/IO2 Riser1 2*PCIe5.0 X16,1*2	1
BC82LCIA	Manufactured Board,BC82LCIA	1
BC15PRUI	Manufactured Board,2288H V7,BC15PRUI, IO3 Riser2 2*PCIe4.0 X8,1*3	1
BC15HBBI	Manufactured Board,2288H V7,BC15HBBI, IO3 4*SAS/SATA/NVMe HDD backplane,1*4	1
BC15HBBE	Manufactured Board,2288H V7,BC15HBBE, IO1/IO2 2*2.5" SAS/SATA HDD backplane,2*2	1
BC15PRUD	Manufactured Board,2288H V7,BC15PRUD, IO1/IO2 Riser4 1*PCIe4.0 X16,1*6	1
BC15PRUC	Manufactured Board,2288H V7,BC15PRUC,	1

	IO1/IO2 Riser3 2*PCIe5.0 X16,1*1	
BC15MSMA	Manufactured Board,1288H V7,BC15MSMA,inner M.2 adapter, support PCH SATA/PCIe,1*1	1
BC15PRUK	Manufactured Board,1288H V7,BC15PRUK, Riser2 1*PCIe5.0 X16,1*4	1
BC15NHBB	Manufactured Board,2288H V7,BC15NHBB, 24*NVMe(include 8*SAS/SATA) HDD backplane,1*2	1
BC15HBBB	Manufactured Board,2288H V7,BC15HBBB, 12*3.5" SAS/SATA (4*NVMe) HDD backplane,1*2	1
BC15PRUF	Manufactured Board,2288H V7,BC15PRUF, IO3 Riser1 2*PCIe4.0 X16,1*2	1
BC15PRUE	Manufactured Board,2288H V7,BC15PRUE, IO1/IO2 Riser5 1*PCIe4.0 X16,1*1	1
BC15PRUB	Manufactured Board,2288H V7,BC15PRUB, IO1/IO2 Riser2 1*PCIe5.0 X16+2*PCIe4.0 X8,1*2	1
BC15FDCA	Manufactured Board,2288H V7,BC15FDCA, Fan Board 4*8080+/8038+,1*3	1
BC15PRUCC	Manufactured Board,2158H V8,BC15PRUCC, AMD Server 2U1P IO1/IO2 Riser6 1*PCIe5.0 X16,1*1	1
BC15PRUCB	Manufactured Board,2158H V8,BC15PRUCB,AMD Server 2U1P Riser Card special for DPU IO1/IO2-1*PCIe5.0 X16,1*1	1
BC15RCIAB	Manufactured Board,2158H V8,BC15RCIAB, AMD Server 2U1P Right Customer Interface Board,1*1	1
BC26MBTAB	Manufactured Board,2158H V8,BC26MBTAB, AMD Server 2U1P Main Board-Genoa,1*1	1
Subassembly list		
Subassembly Name	Description	
PCIE Card	Manufactured Board,Public Module,BC51ETHK1, XP382 Ethernet Adapter,25GE(Mellanox CX-5 Lx),Dual-Port,SFP28(without Optical Transceiver),PCIE 3.0 x8,Vendor ID 15b3-Device ID 1017-2,1*2	
PCIE Card	Manufactured Board,Public Module,CN21ITGG1,XP330 Ethernet Adapter,10Gb Optical Interface(Intel X710),2-Port,SFP+(without Optical Transceiver),PCIE 3.0 X8-Vendor ID 8086-Device ID 1572-2,1*2	
PCIE Card	Manufactured Board,Public Module,CN21ITGC1,XP212 I350 4*GE PCIE Card,PCIE 2.0 X4-Vendor ID 8086-Device ID 1521-4,1*2	
GPU Card	GPU Card,NVIDIA L20 GPU Accelerator,PN:900-2G133-00A0-000 / 48GB GDDR6 Memory / 864GB/s Memory Bandwidth /PCIE 4.0 x16-10DE-26BA-1 /350W,No NVLink,English doc,Dual slot,Passive	
PCIE Card	Network Card,100Gb/s,64bit,QSFP112,2 Ports,PCIE 5.0 X16-Vendor ID 15b3-Device ID a2dcjc2d5-3-Subvendor ID 15B3-Subdevice ID 0035, No Driver CD,NVIDIA BlueField B3210E No Crypto-Single-Slot-32GB DDR5- FHHL,Baidu,AVAP	
PCIE Card	Network Card,100 Gigabit,64bit,QSFP28,2 ports,PCIE 4.0 x16-14e4-1750-2, No Driver CD,KUAISHOU,AVAP	
PCIE Card	Network Card,100 Gigabit,64bit,QSFP28,2 ports,PCIE 4.0 x16-14e4-1750-	

	2,No Driver CD,OCP,KUAISHOU,AVAP
PCIE Card	Network Card,100 Gigabit,64bit,QSFP28,2 ports, PCIE 4.0 x16-14e4-1750-2,No Driver CD,OCP
PCIE Card	Network Card,25 GE,64bit,SFP28,2,PCIE 4.0 x8-15b3-101f-2, No Driver CD,Meituan,AVAP
PCIE Card	Network Card,25 GE,64bit,SFP28,2,PCIE 4.0 x8-15b3-101f-2,No Driver CD
PCIE Card	Network Card,100GE,64bit,QSFP56(without Optical Transceiver), 2 Ports,PCIE 4.0 x16-15b3-101d-2,No Driver CD,Meituan,AVAP
PCIE Card	Network Card,100GE,64bit,QSFP56(without Optical Transceiver), 2 Ports,PCIE 4.0 x16-15b3-101d-2,No Driver CD,KUAISHOU,AVAP
PCIE Card	Network Card,100GE,64bit,QSFP56(without Optical Transceiver), 2 Ports,PCIE 4.0 x16-15b3-101d-2,No Driver CD
PCIE Card	Network Card,25Gb/s,64bit,SFP28,2 ports,PCIE 4.0 x8-15b3-101f-2, No Driver CD,OCP
PCIE Card	IB Card,Infiniband MCX75310AAS-HEAT,200Gb/s NDR200 IB, single port OSFP,PCIE 5.0 x16-Vendor ID 15B3-Device ID 1021-1-Subvendor ID 15B3-Subdevice ID 0029,English doc,(IB&Ethernet)
PCIE Card	IB Card,Infiniband MCX653105A-HDAT,200Gb/s-64bit-QSFP56-1port,PCIE 4.0 x16-Vendor ID 15b3-Device ID 101b-1-Subvendor ID 15b3-Subdevice ID 0007,Chinese and English doc
RAID Card	Other Cards,PCIE 4.0 X8-Vendor ID 1000-Device ID 10E6-1-Subvendor ID 1000-Subdevice ID 40D5-12G SAS RAID,x8 PCIe 4.0-9540-8i SAS RAID Card,SAS3808,No CacheVault,12Gb/s SAS,6Gb/s SATA,PCIe(NVMe), 9540-8i,Chinese doc,1pcs bracket
RAID Card	Other Cards,PCIE 4.0 X8-Vendor ID 1000-Device ID 10E2-1-Subvendor ID 1000-Subdevice ID 4000-12G SAS RAID card,x8 PCIe 4.0-9560-16i SAS RAID Card,SAS3916,8G CacheVault,CVPM05-12Gb/s SAS, 6Gb/s SATA,PCIe(NVMe),9560-16i,English doc
RAID Card	Other Cards,PCIE 4.0 X8-Vendor ID 1000-Device ID 10E2-1-Subvendor ID 1000-Subdevice ID 4010-12G SAS RAID card,x8 PCIe 4.0-9560-8i SAS RAID Card,SAS3908,4G CacheVault,CVPM05-12Gb/s SAS, 6Gb/s SATA,PCIe(NVMe),9560-8i,Chinese and English doc
PCIE Card	Manufactured Board-JDM,Public Module,BC53ETHI,XC386 OCP3.0 Ethernet Adapter-25GE(BCM57414)-Dual Port-SFP28(without Optical Module)-PCIE 3.0 X8-Vendor ID 14e4-Device ID 16d7-2-Subvendor ID 1f24-Subdevice ID 2013,1*4
PCIE Card	Manufactured Board-JDM,Public Module,BC55ETHA,XC385 OCP3.0 Ethernet Adapter-25GE(CX6-Lx)-Dual Port-SFP28(without Optical Module)-PCIE 4.0 X8-Vendor ID 15b3-Device ID 101f-2-Subvendor ID 1f24-Subdevice ID 2011,1*4
PCIE Card	Manufactured Board-JDM,Public Module,BC53ETHH,XC331 OCP3.0 Ethernet Adapter-10GE(BCM57416)-Dual Port,RJ45-PCIE 3.0 X8-Vendor ID 14e4-Device ID 16d8-2-Subvendor ID 1f24-Subdevice ID 2010,1*3
PCIE Card	Manufactured Board-JDM,Public Module,BC53ETHG,XC383 OCP3.0 Ethernet Card-10GE(CX-4 Lx)-Dual Port-SFP+(without optical module)-PCIE

	3.0 X8-Vendor ID 15b3-Device ID 1015-2-Subvendor ID 1f24-Subdevice ID 200d,1*4
Power Supply	2000W AC power supply
Power Supply	900W AC power supply
Power Supply	1500W AC power supply
Power Supply	1500W HVDC power supply
Power Supply	3000W AC power supply
Battery	Original Battery, Round, D20*3.2mm
CPU Module	AMD CPU
Memory Module	DDR5-RDIMM
SSD Module	SSD
FAN	Fan Assembly

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Annex III Typical Configuration of Product

Board list		
Board Name	Description	Qty.
BC26MBTA	Manufactured Board,2158H V8,BC26MBTA, AMD Server 2U1P Main Board,1*1	1
BC82LCIA	Manufactured Board, BC82LCIA, Left Customer Interface,4*2	1
BC15RCIAB	Manufactured Board,2158H V8,BC15RCIAB, AMD Server 2U1P Right Customer Interface Board,1*1	1
BC15NHBK,	Manufactured Board,2288H V7,BC15NHBK, 8*2.5" SAS/SATA/NVMe HDD backplane,1*2	1
BC26FDTA	Manufactured Board,2158H V8,BC26FDTA, AMD Server 2U1P Fan Board 6*6056,1*2	1
Subassembly list		
Subassembly Name	Description	
PCIE Card	Network Card,100GE,64bit,QSFP56(without Optical Transceiver), 2 Ports,PCIE 4.0 x16-15b3-101d-2,No Driver CD	
IO Extended Module	IO Extended Module-PCIE, 2288H V7,BC1M01PRUE, 1*16X SLOT(PCIE4.0)-SLOT2-Riser1&2 module	
CPU Module	CPU Module,Server,AMD9754CPU01,AMD Genoa 9754 (2.25GHz/128-Core/256MB/360W)CPU(with 2U body 2U special heat sink)	
Memory Module	Memory Module,DDR5-RDIMM,128GB,288pin,0.312ns,6400000KHz, 1.1V,ECC,2Rank(8G*4bit)	
SSD Module	SSD Module,Servers,SSD,1920GB,NVMe PCIe,Read Intensive,UH711a-Y Series,2.5inch(2.5inch Drive Bay),V7 dedicated	
SSD Module	SSD Module,Servers,SSD,480GB,SATA 6Gb/s,Read intensive, ER3 Series,2.5inch(2.5inch Drive Bay),V7 dedicated	
FAN	Function Module,2158H V8,BC1M22FAN01,6056Fan module	
Power Supply	Function Module,PAC2000S12-B1,Server Platinum 2000W Version 2.0 AC power supply	

END